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(12) United States Design Patent

Kataoka et al.

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(45) Date of Patent: ** Aug. 11, 2009

(54) **INFRARED RADIATION SENSOR**

(75) Inventors: **Tomohiro Kataoka**, Kyoto (JP); **Shinichi Wada**, Kyoto (JP); **Masakazu Shiinoki**, Kyoto (JP)

(73) Assignee: **Omron Corporation**, Kyoto (JP)

(**) Term: **14 Years**

(21) Appl. No.: **29/310,989**

(22) Filed: **Jan. 9, 2008**

(30) **Foreign Application Priority Data**

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Jul. 9, 2007 (JP) ..... D 2007-018536
Jul. 9, 2007 (JP) ..... D 2007-018537

(51) **LOC (9) Cl.** **10-04**
(52) **U.S. Cl.** **D10/47**; D10/103
(58) **Field of Classification Search** D10/47, D10/99, 102–103; 102/216; 136/213, 224, 136/235; 250/492.1; 257/E31.117
See application file for complete search history.

(56) **References Cited**

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Primary Examiner—Antoine D Davis

(74) *Attorney, Agent, or Firm*—Harness, Dickey & Pierce PLC

(57) **CLAIM**

The ornamental design for an infrared radiation sensor, as shown and described.

DESCRIPTION

FIG. **1** is perspective view of an infrared radiation sensor showing our new design;

FIG. **2** is a front elevational view thereof;

FIG. **3** is a rear elevational view thereof;

FIG. **4** is a left side view thereof;

FIG. **5** is a right side view thereof;

FIG. **6** is a top plan view thereof;

FIG. **7** is a bottom plan view thereof;

FIG. **8** is a perspective view of an infrared radiation sensor showing a second embodiment of our new design;

FIG. **9** is a front elevational view thereof;

FIG. **10** is a rear elevational view thereof;

FIG. **11** is a left side view thereof;

FIG. **12** is a right side view thereof;

FIG. **13** is a top plan view thereof;

FIG. **14** is a bottom plan view thereof;

FIG. **15** is a perspective view of an infrared radiation sensor showing a second embodiment of our new design;

FIG. **16** is a front elevational view thereof;

FIG. **17** is a rear elevational view thereof;

FIG. **18** is a left side view thereof;

FIG. **19** is a right side view thereof;

FIG. **20** is a top plan view thereof; and,

FIG. **21** is a bottom plan view thereof.

The broken lines shown in the drawings are for illustrative purposes only and form no part of the claimed design.

1 Claim, 12 Drawing Sheets

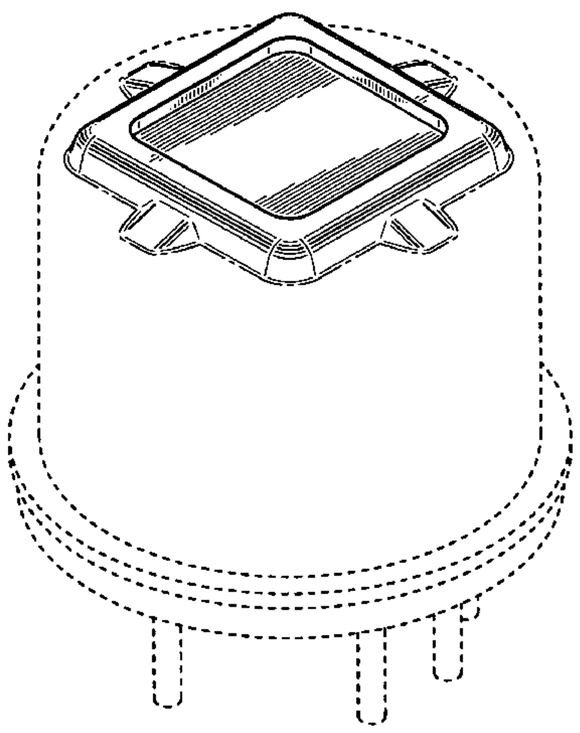

Fig. 1

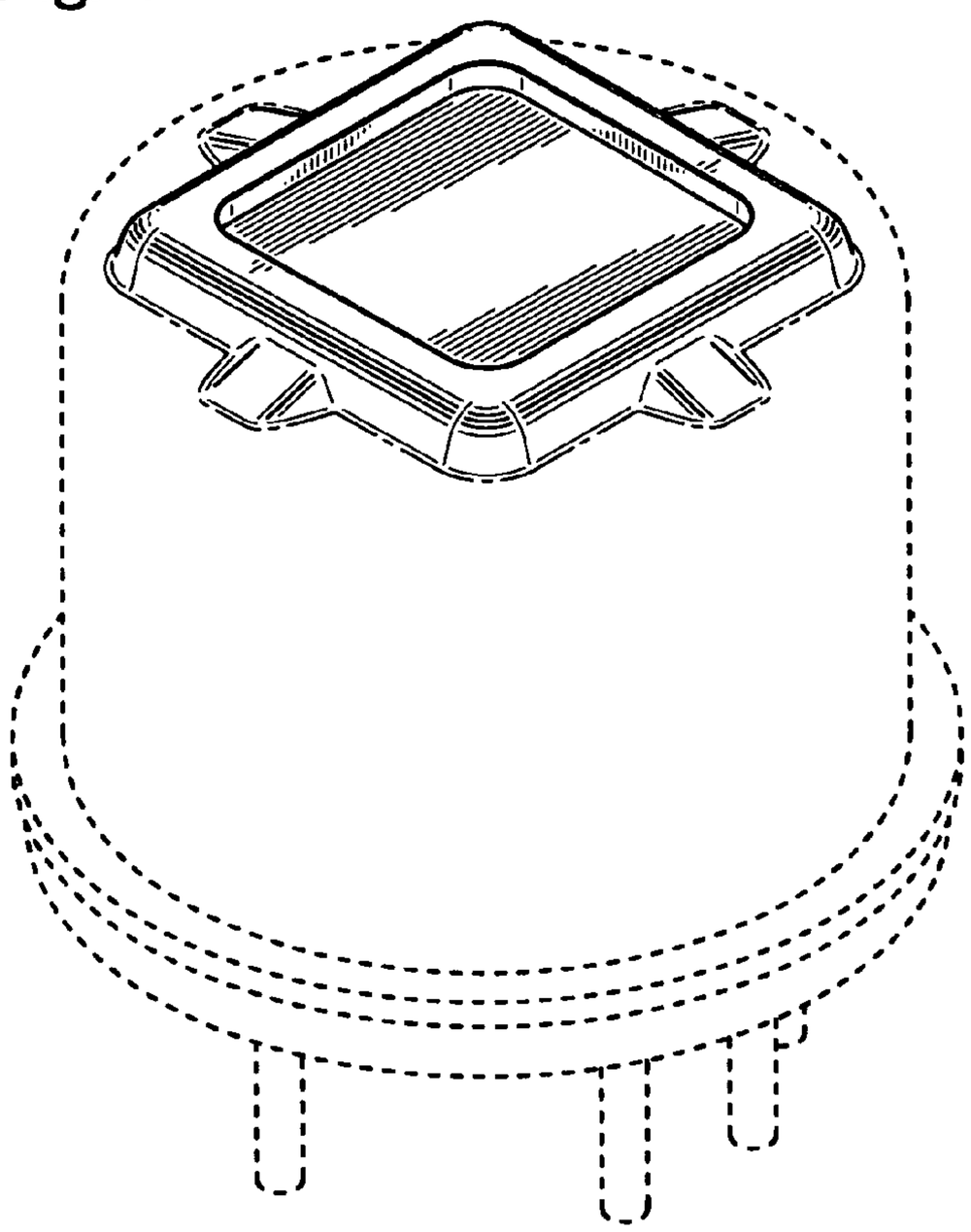

Fig. 2

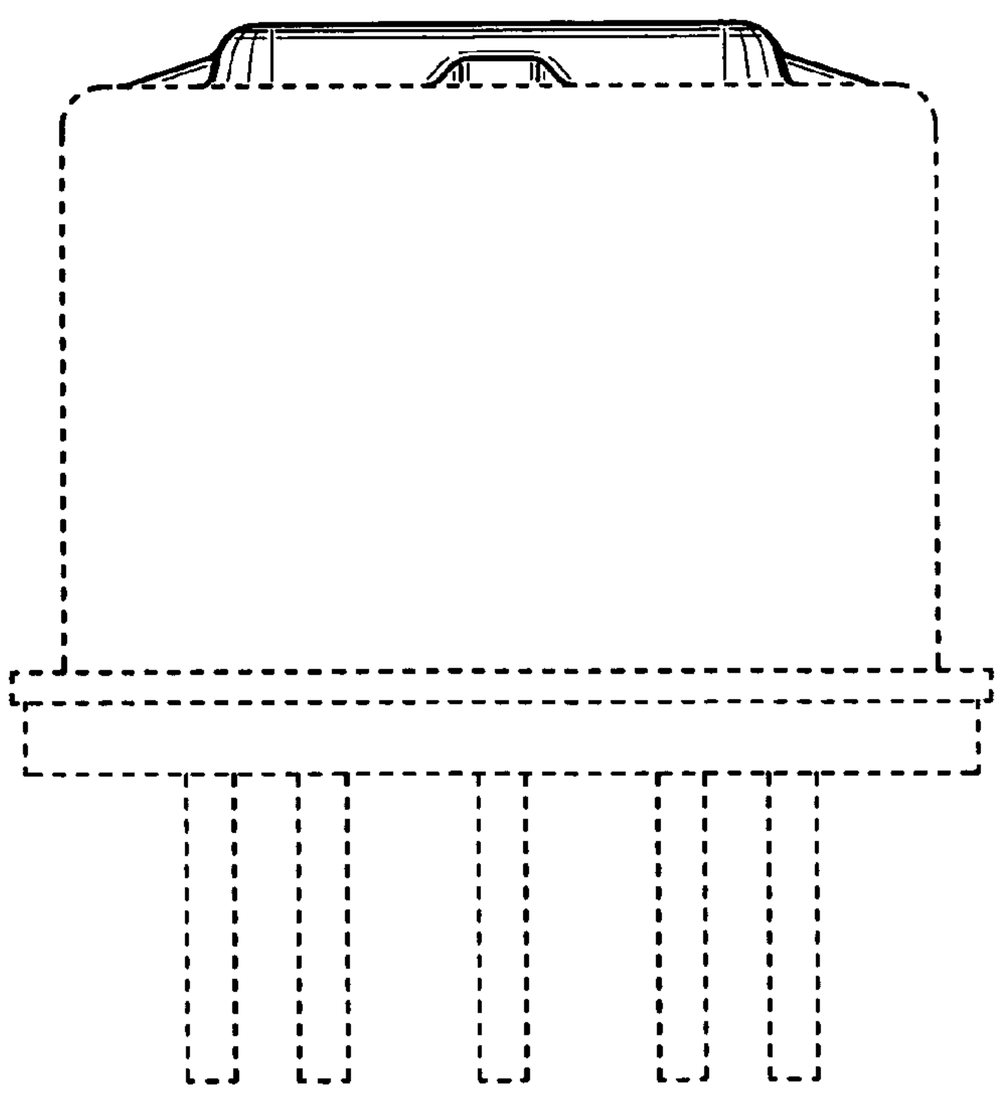

Fig. 3

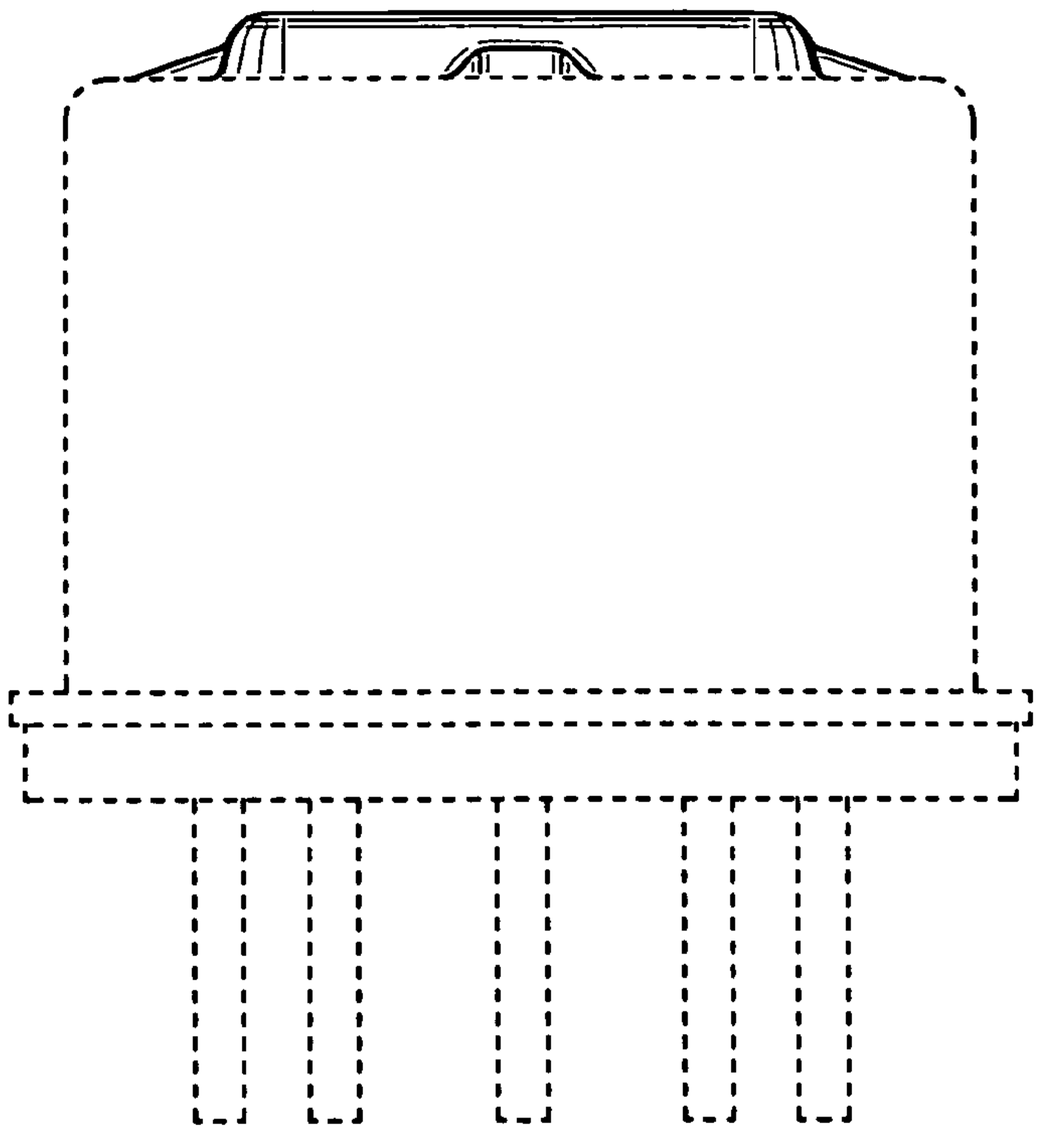

Fig. 4

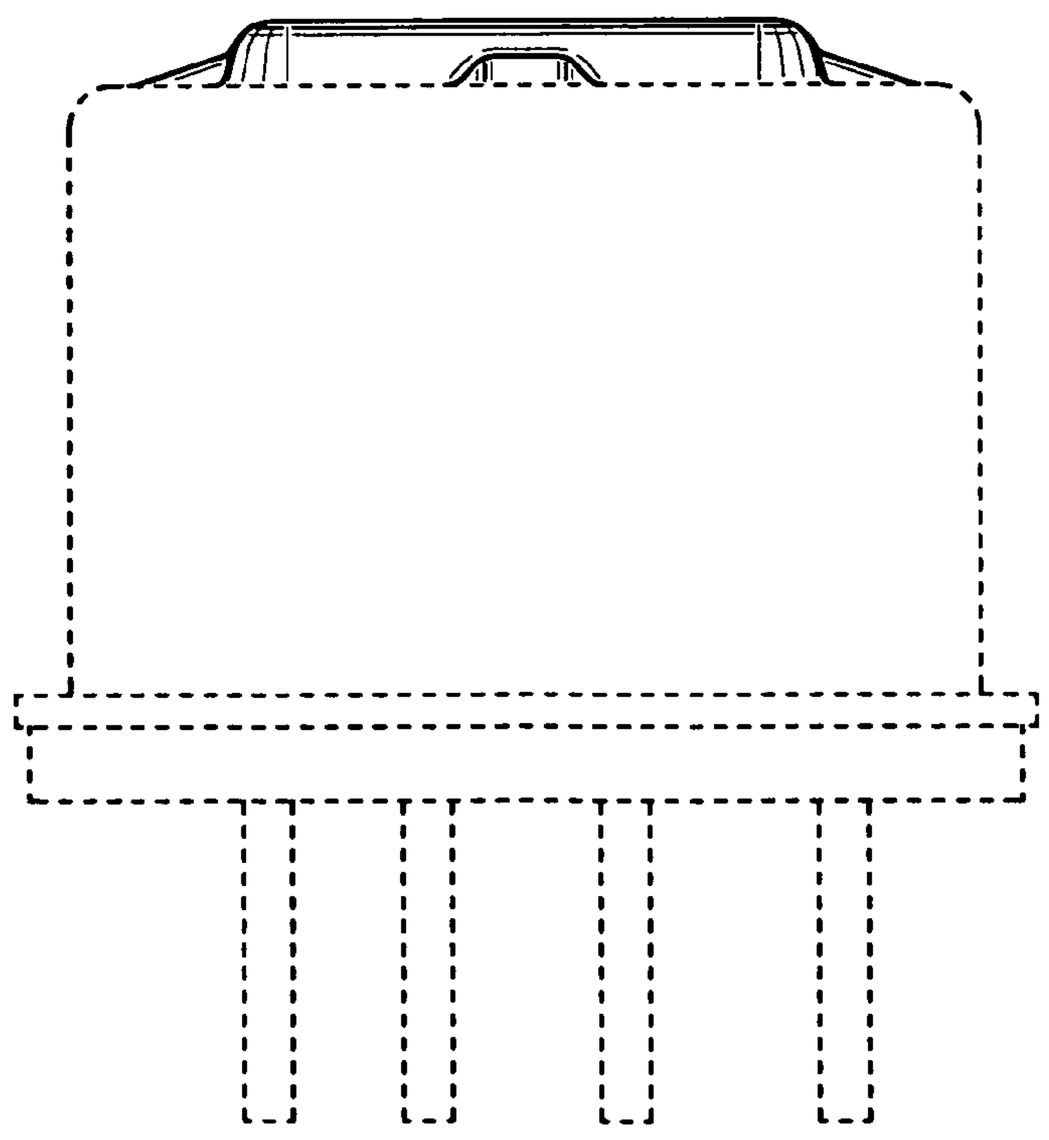

Fig. 5

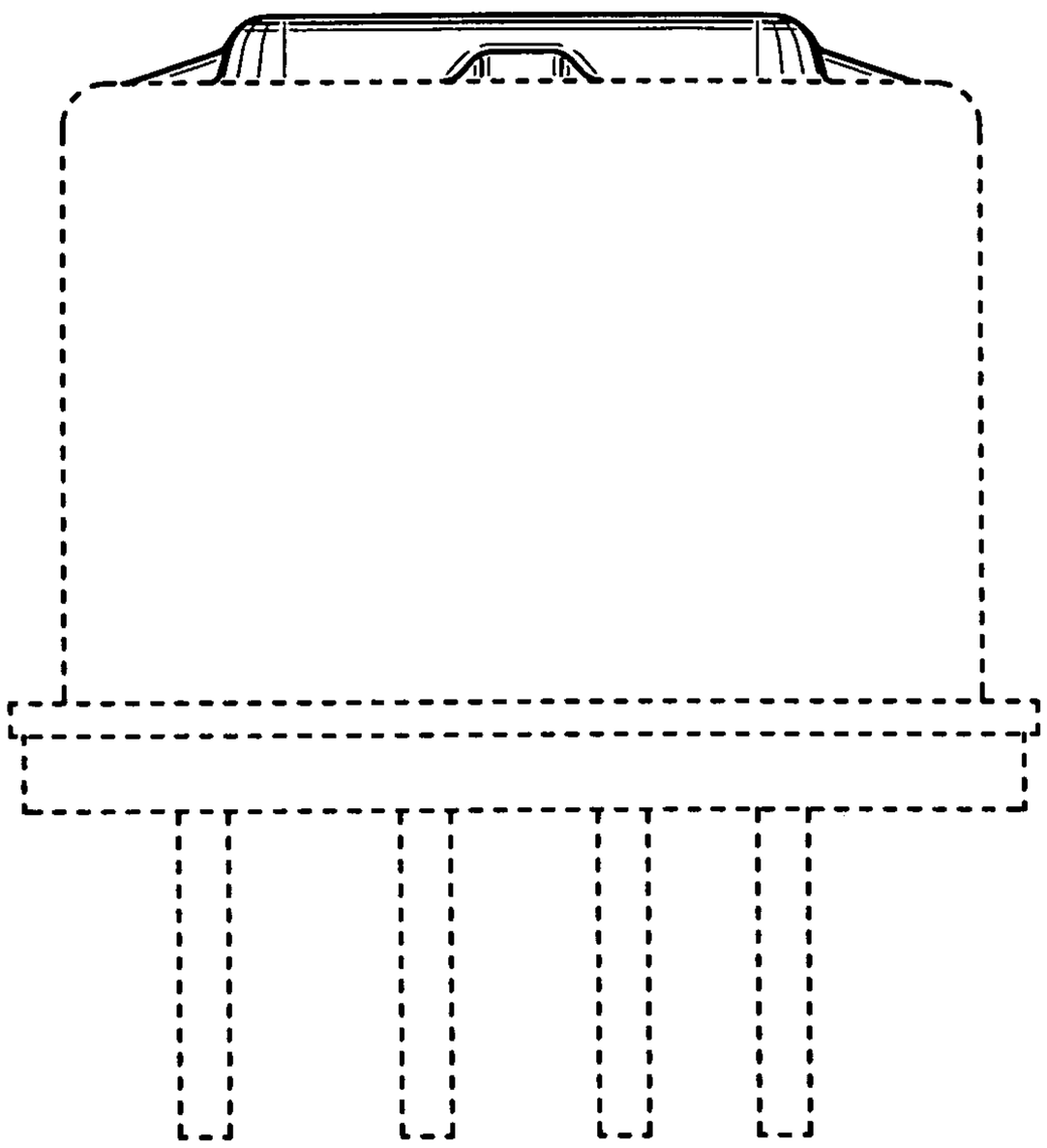

Fig. 6

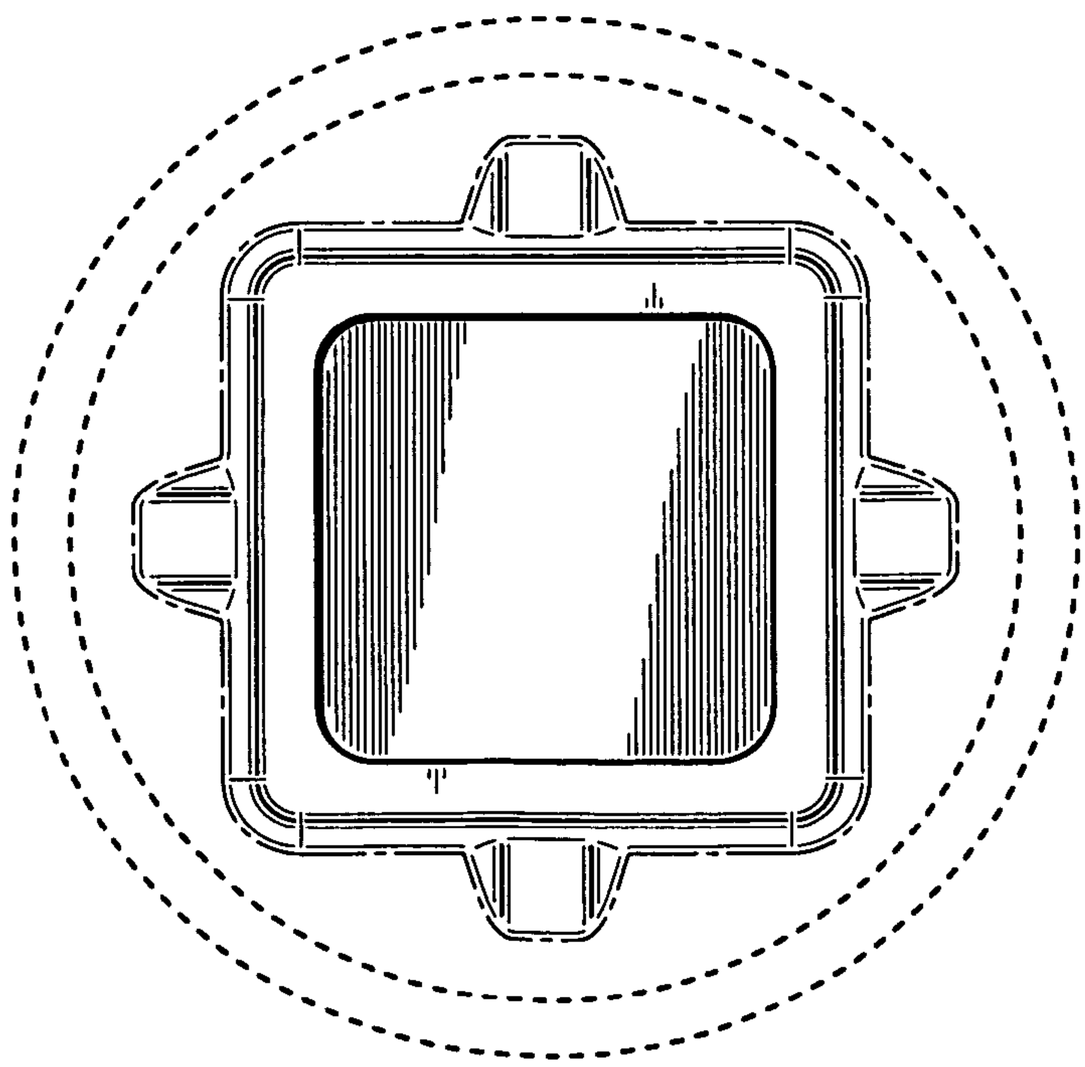

Fig. 7

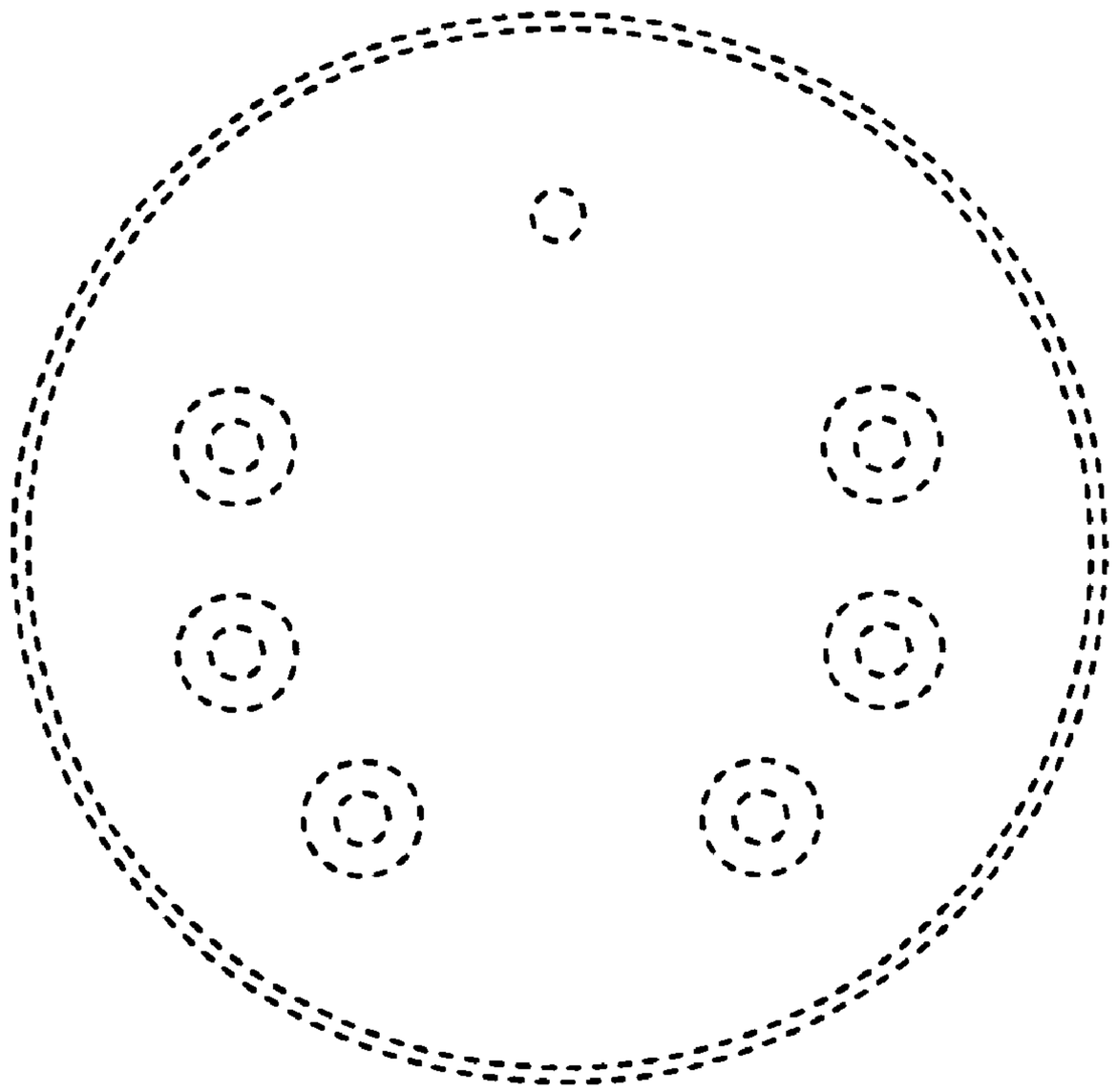

Fig. 8

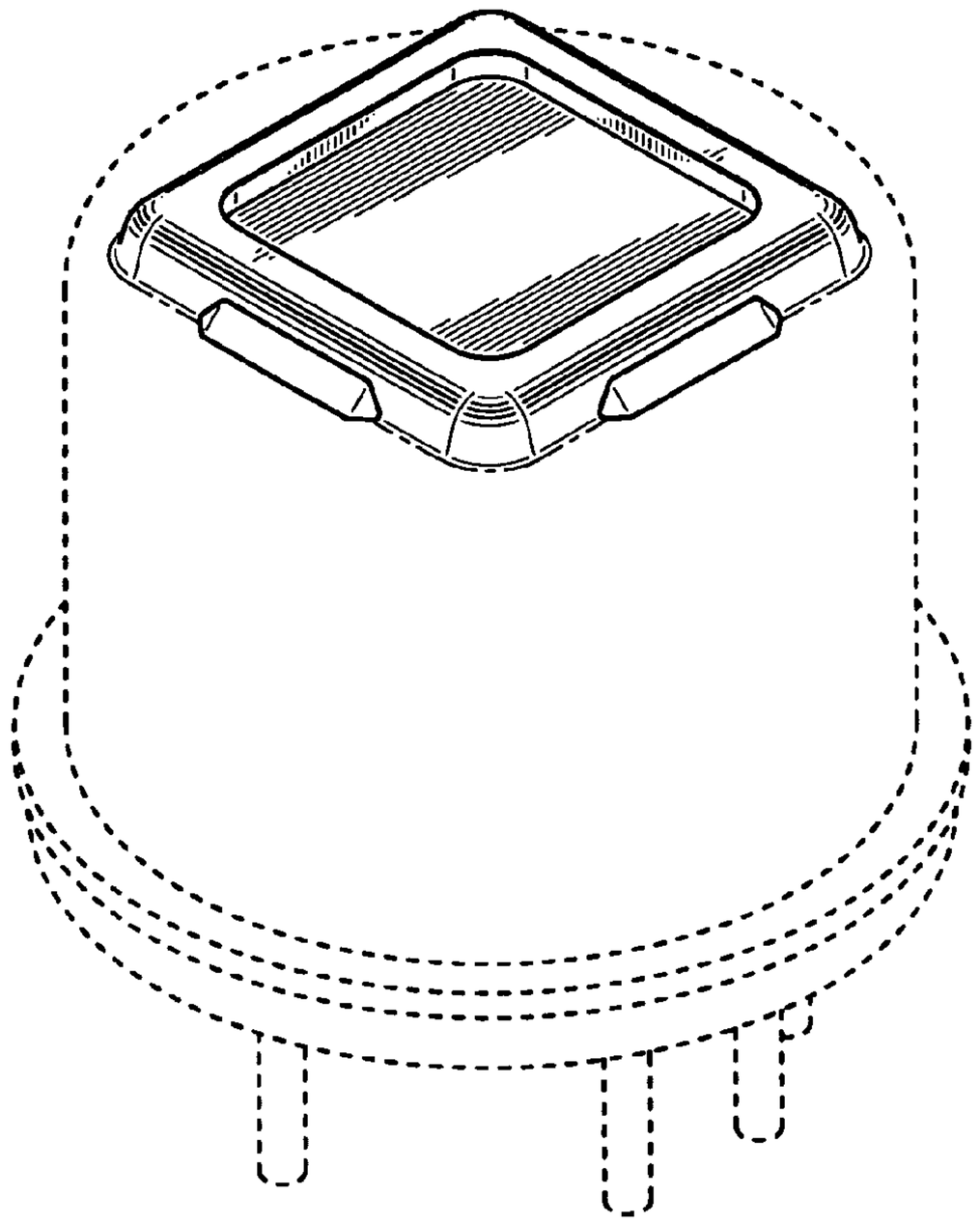

Fig. 9

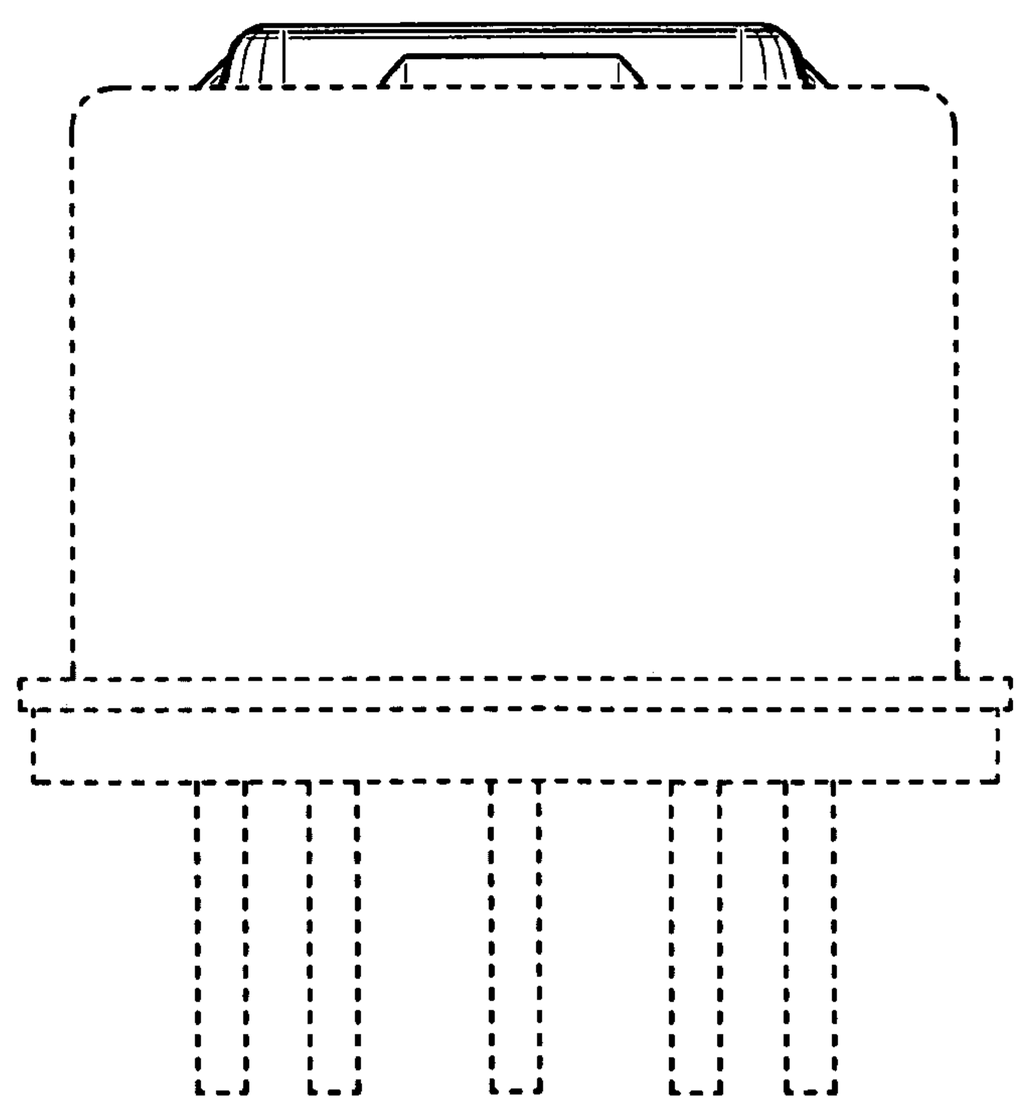

Fig. 10

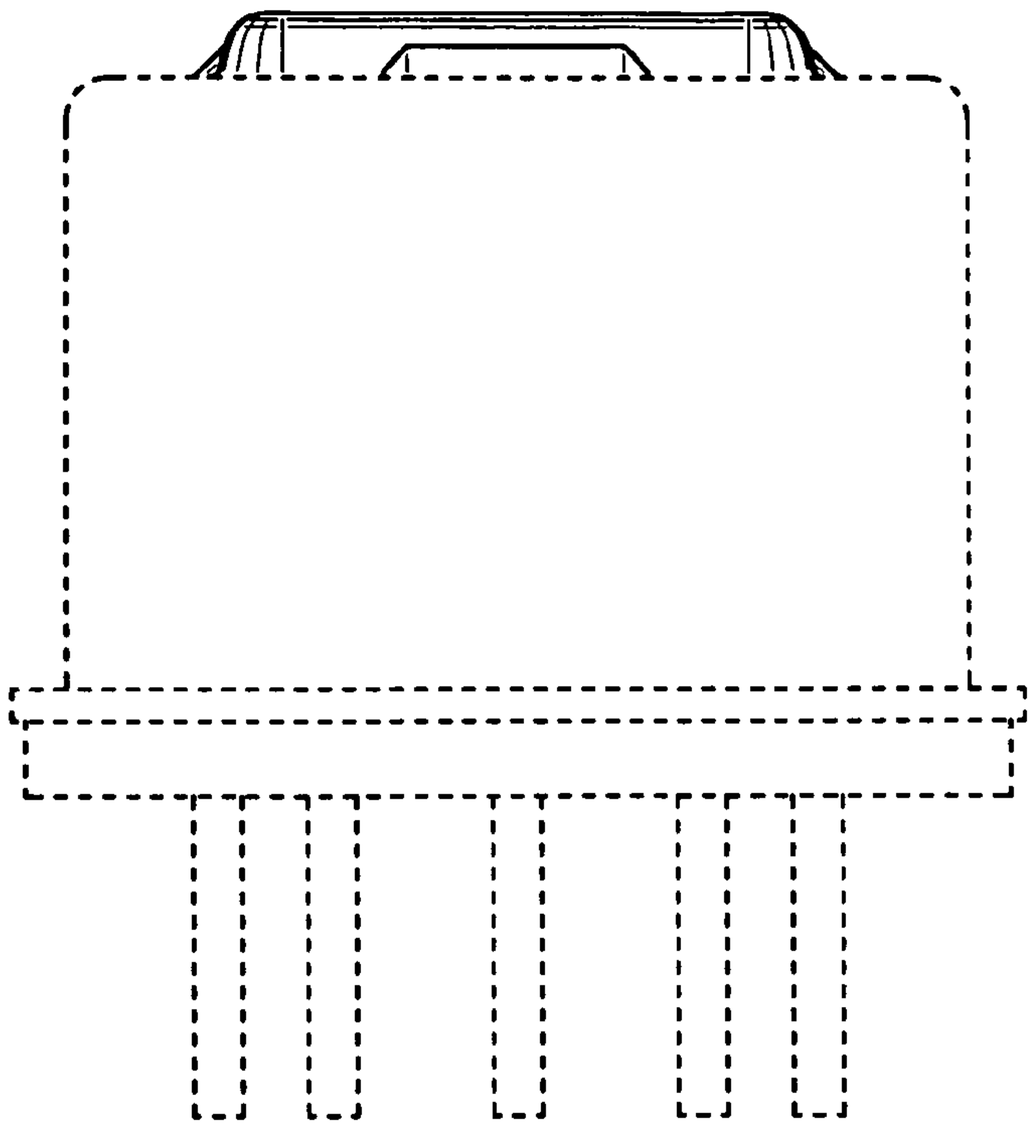

Fig. 11

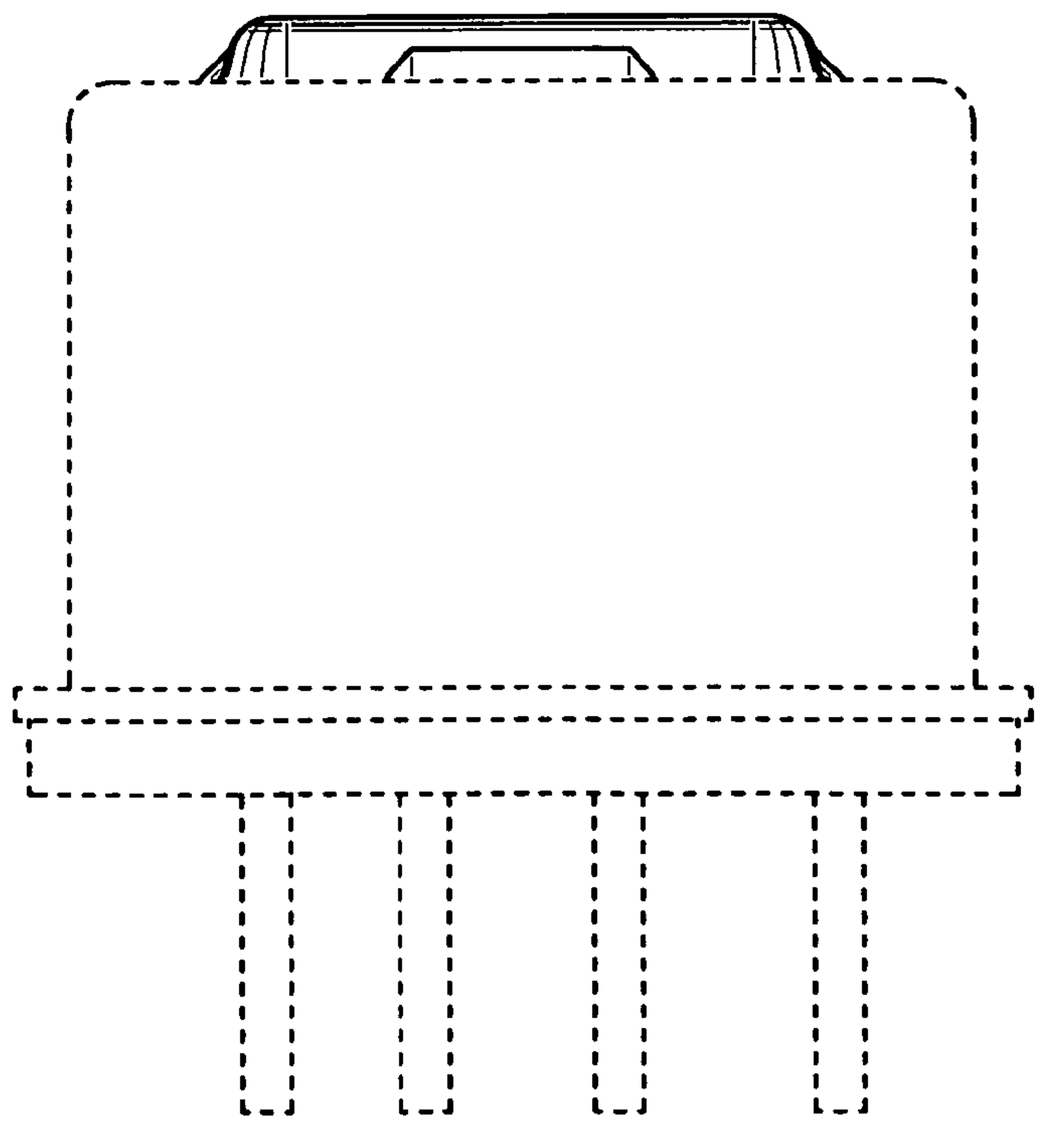

Fig. 12

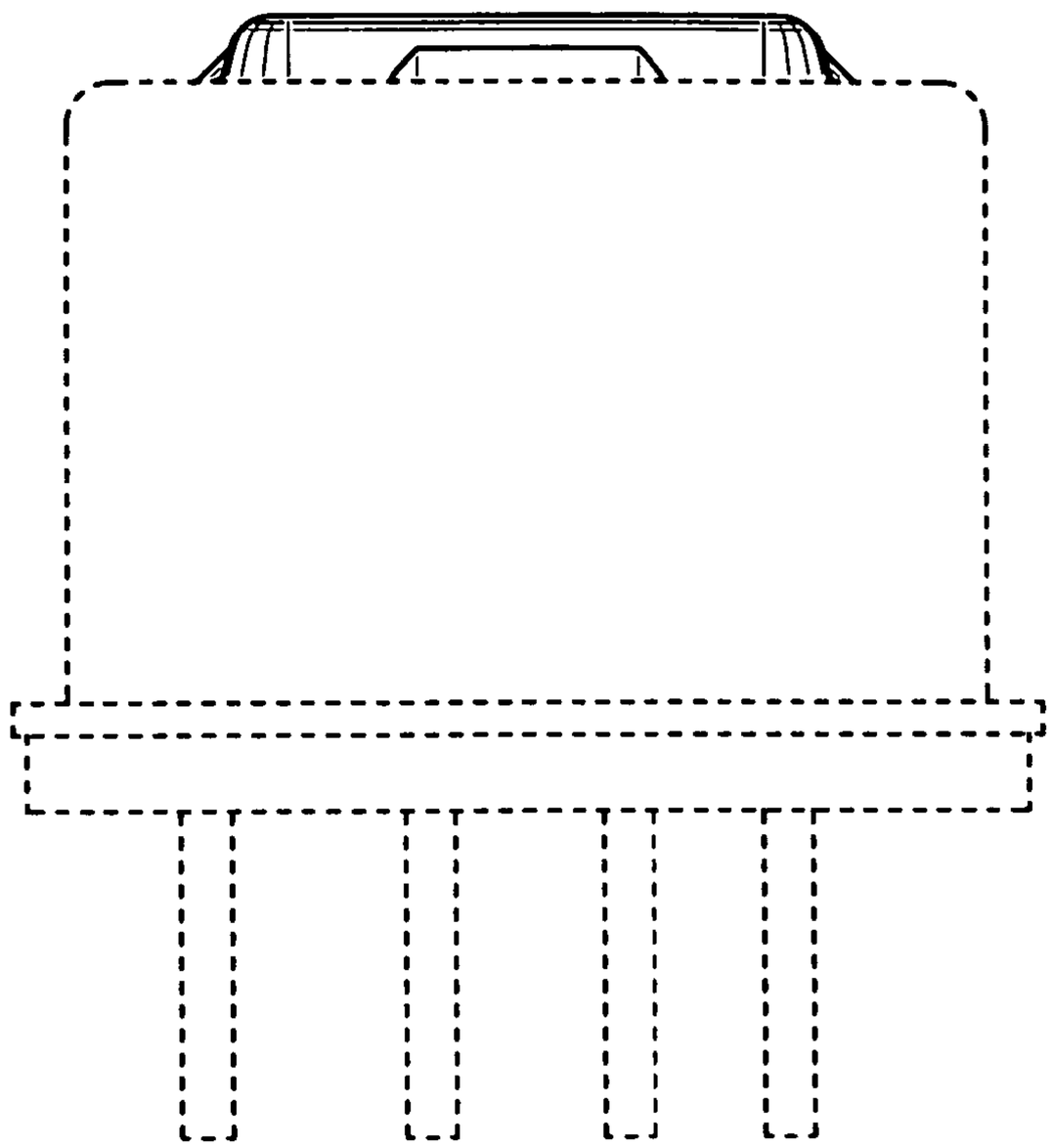

Fig. 13

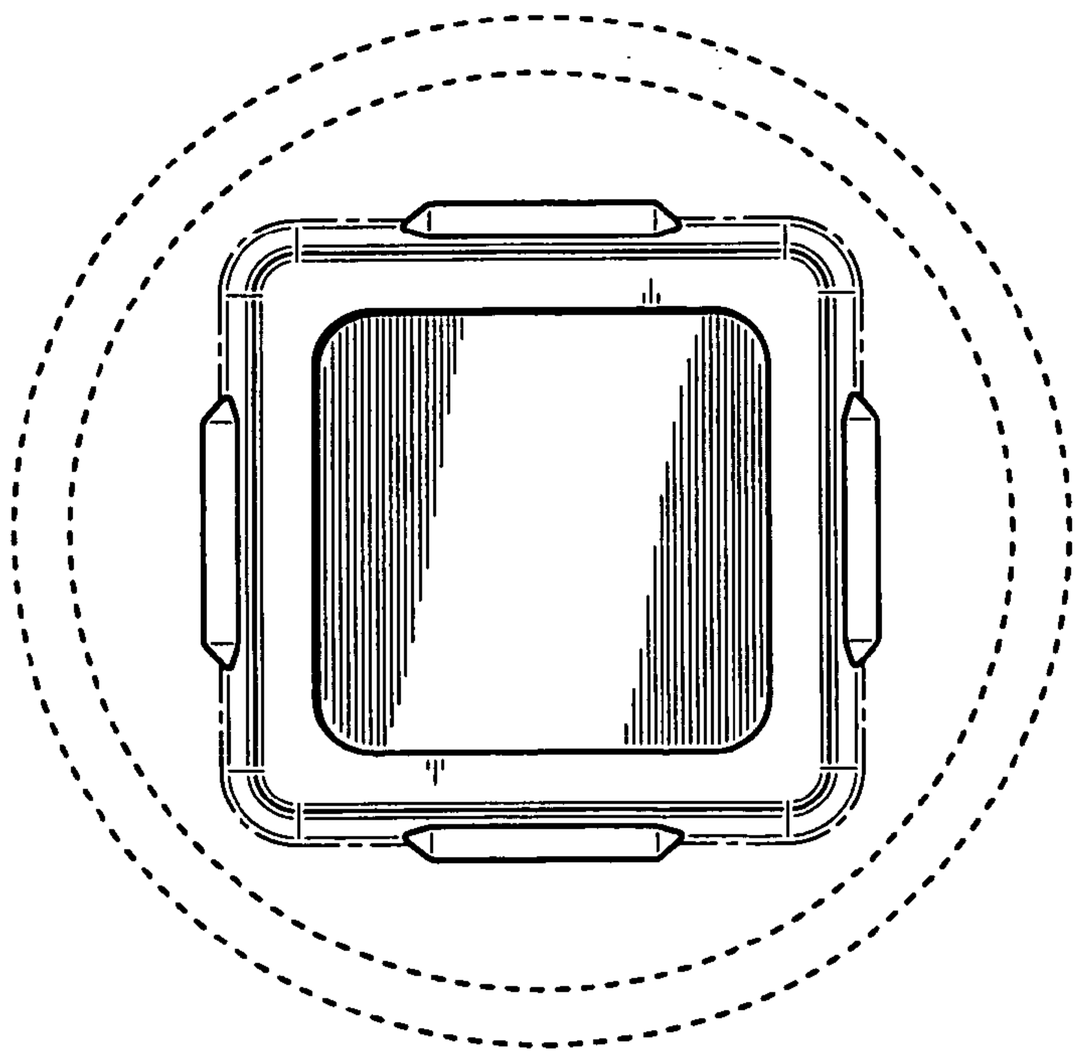

Fig. 14

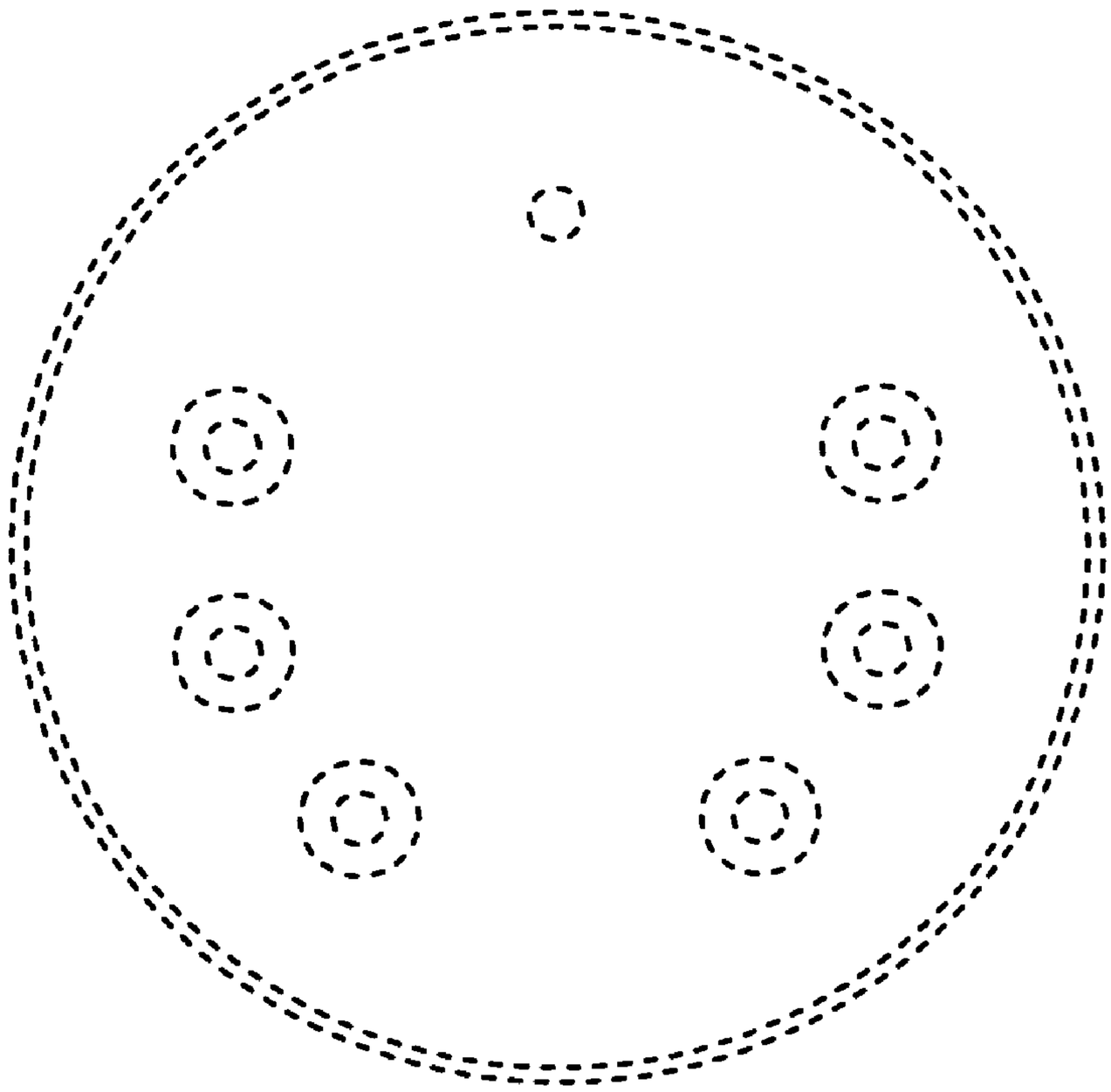

Fig. 15

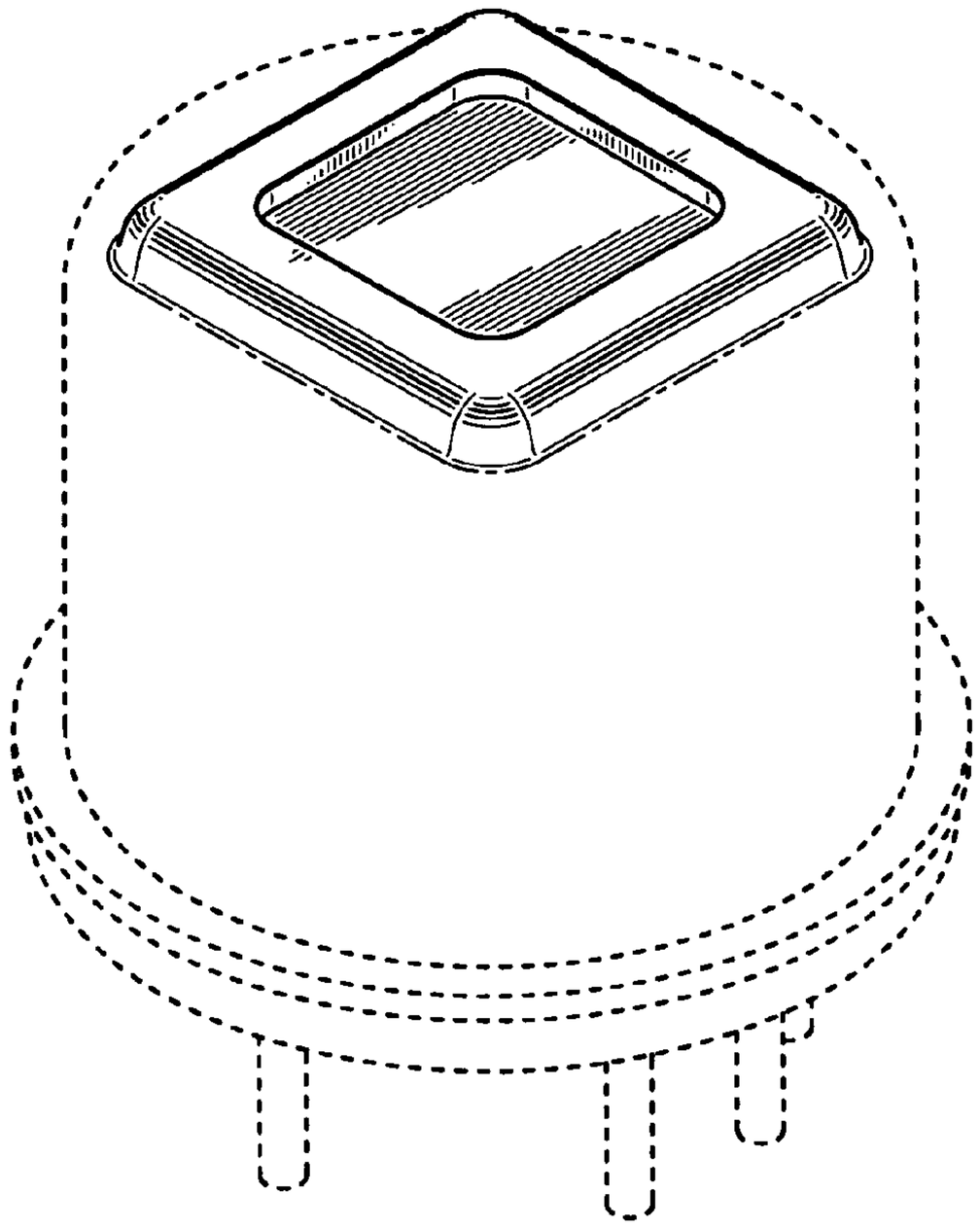

Fig. 16

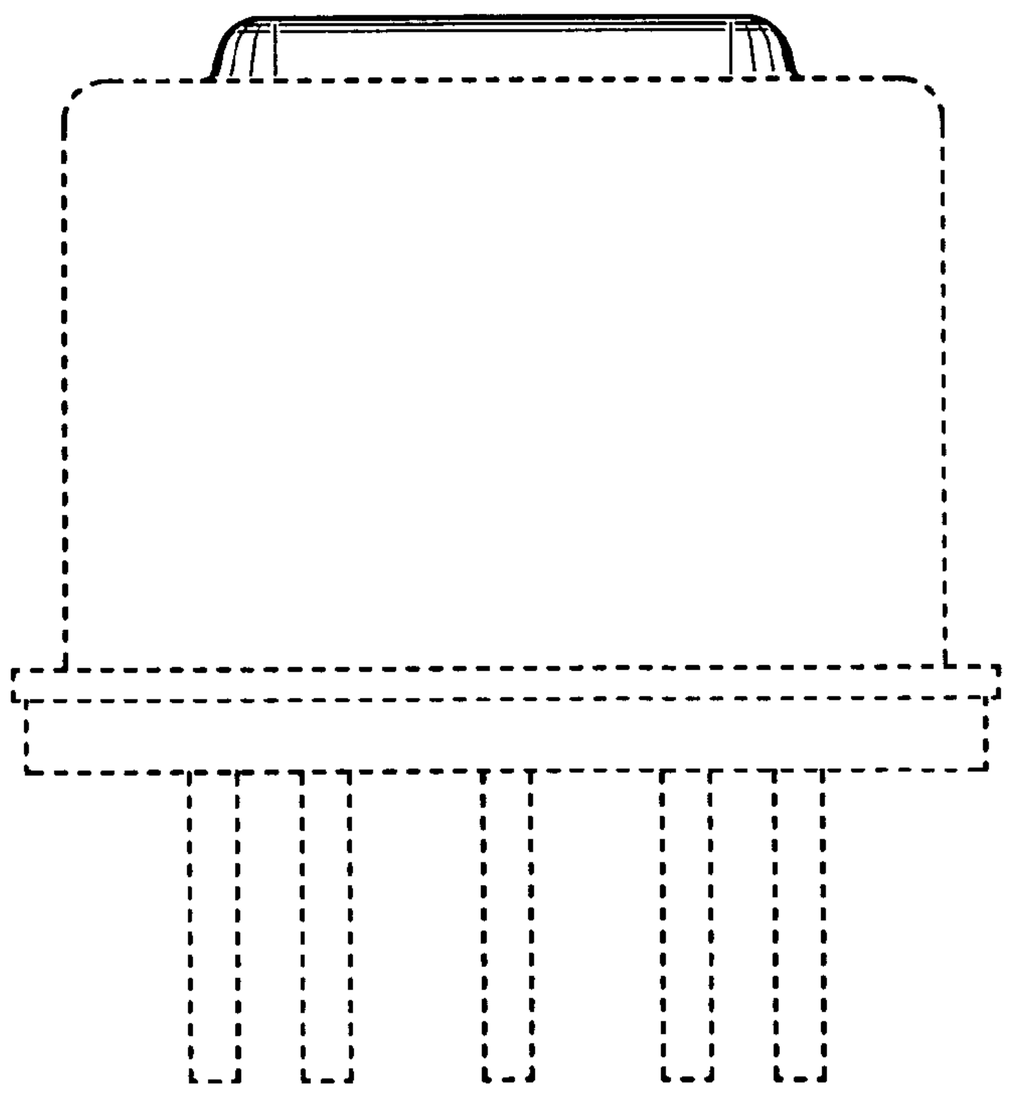

Fig. 17

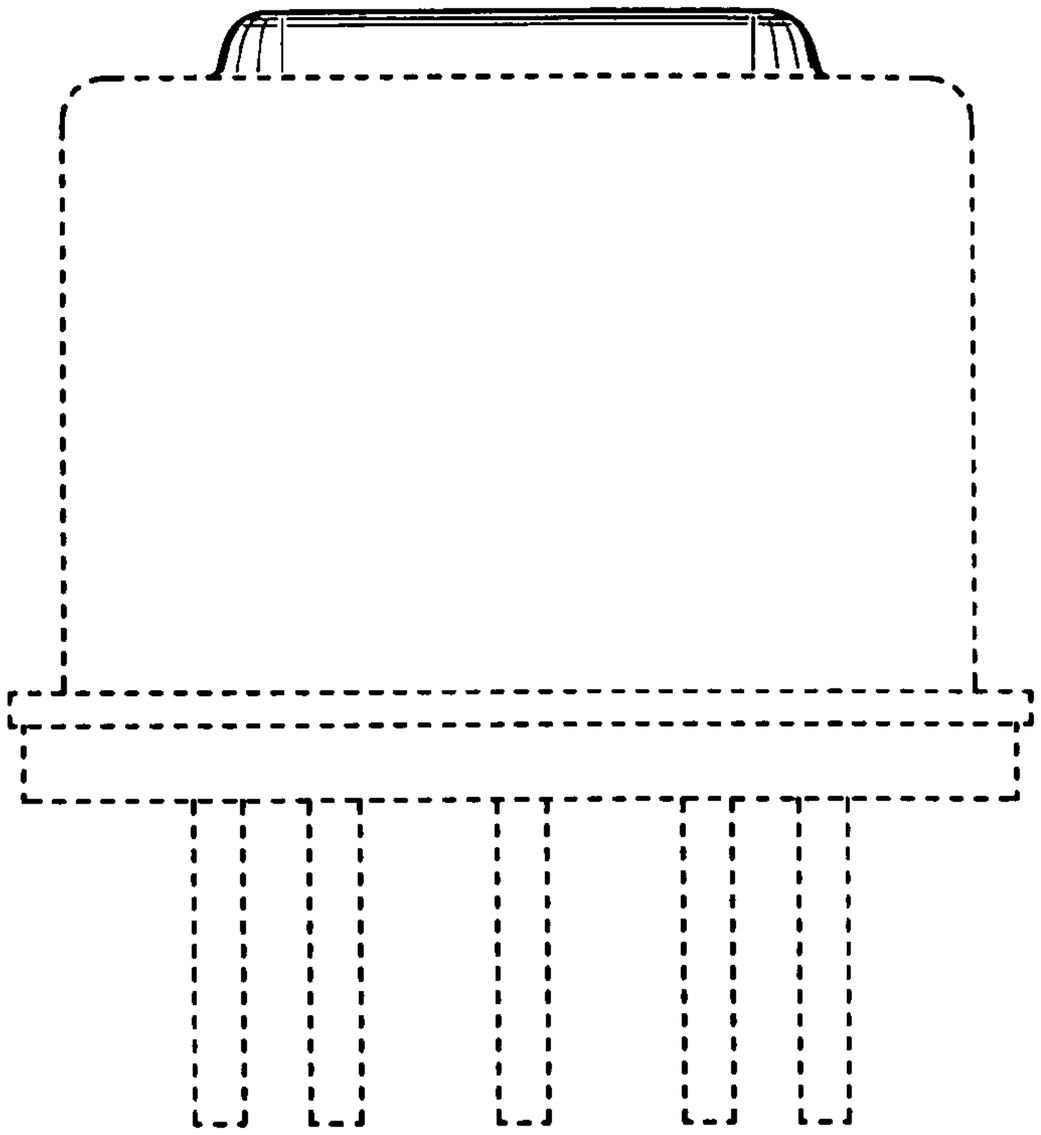

Fig. 18

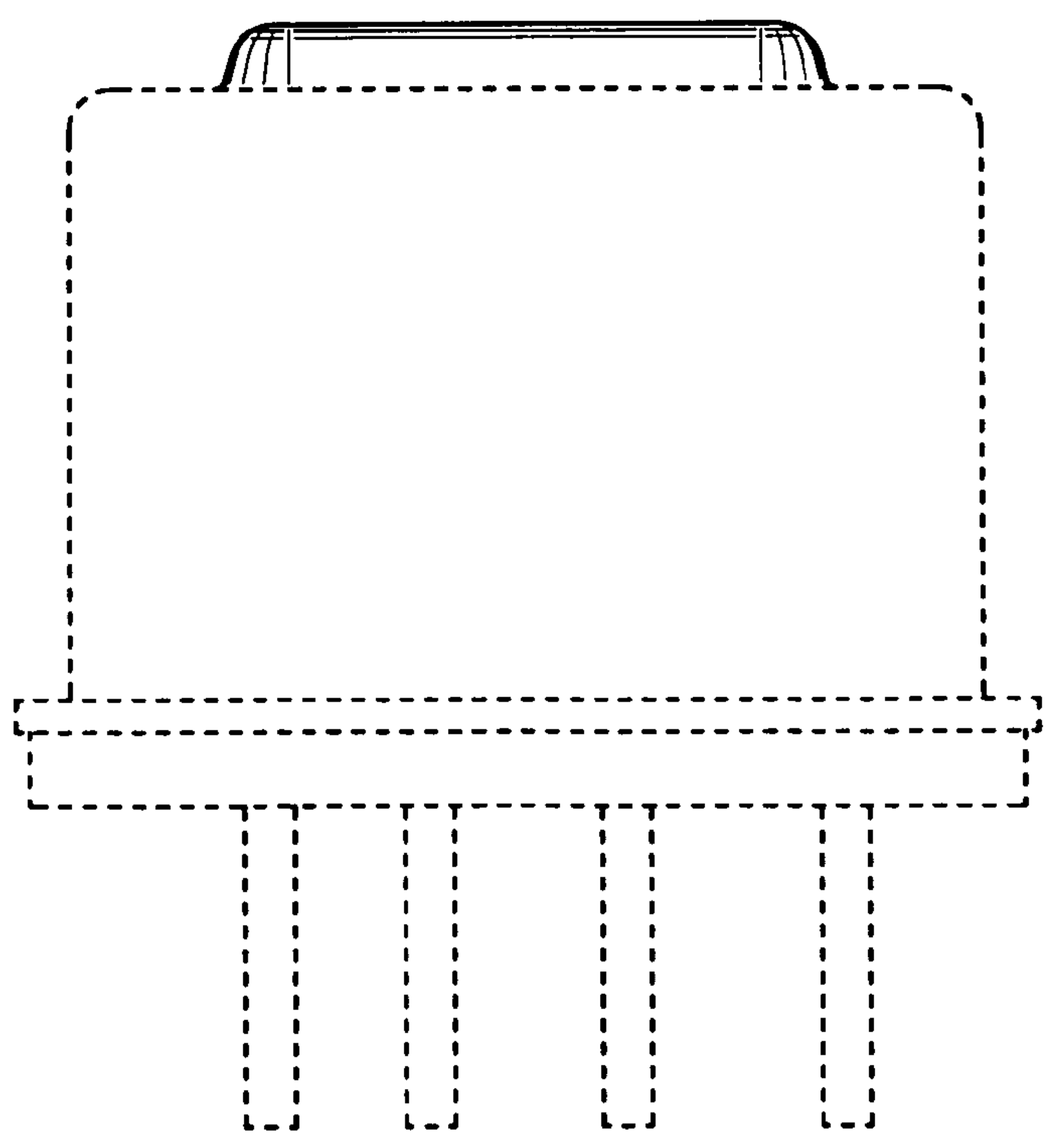

Fig. 19

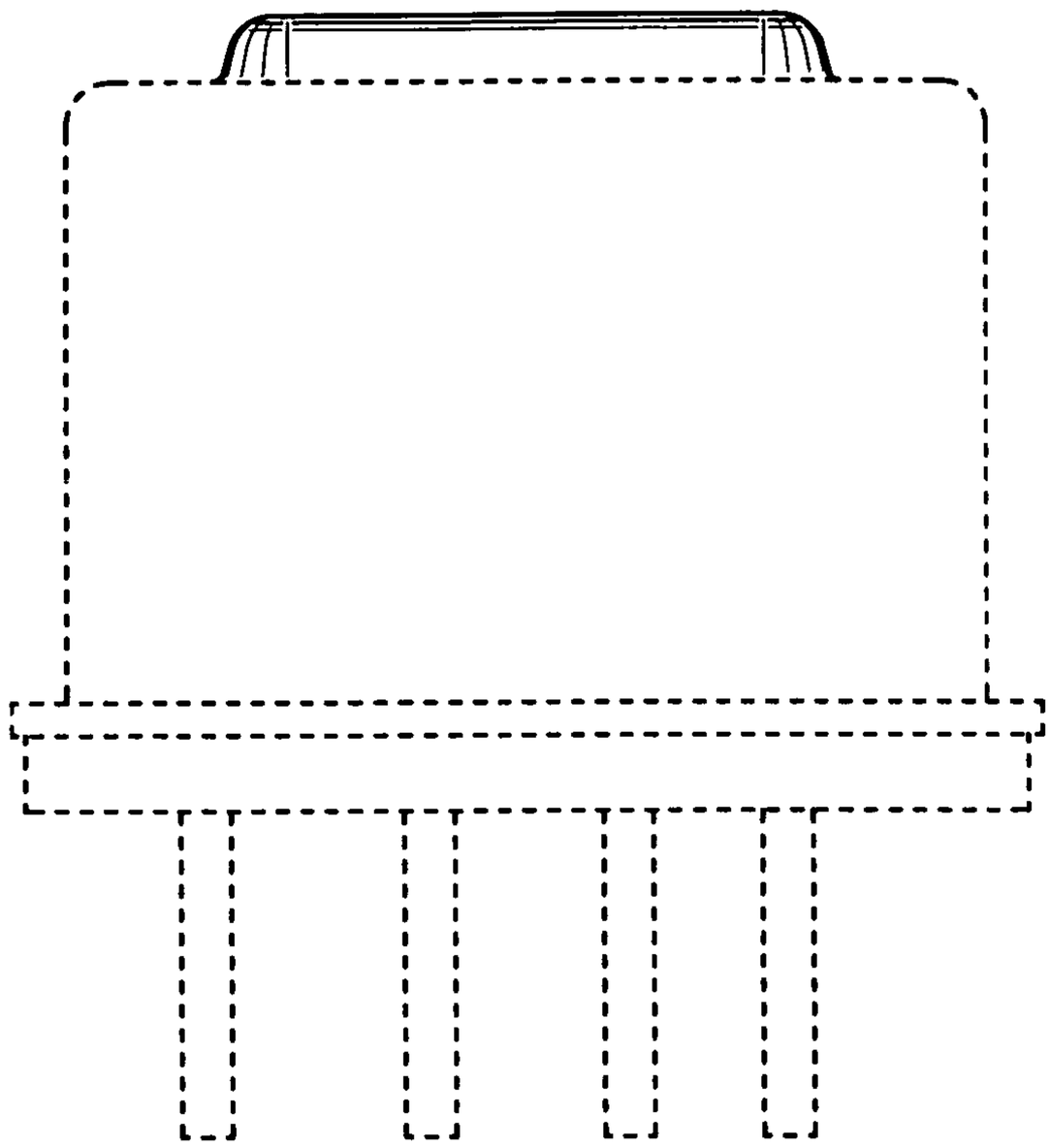

Fig. 20

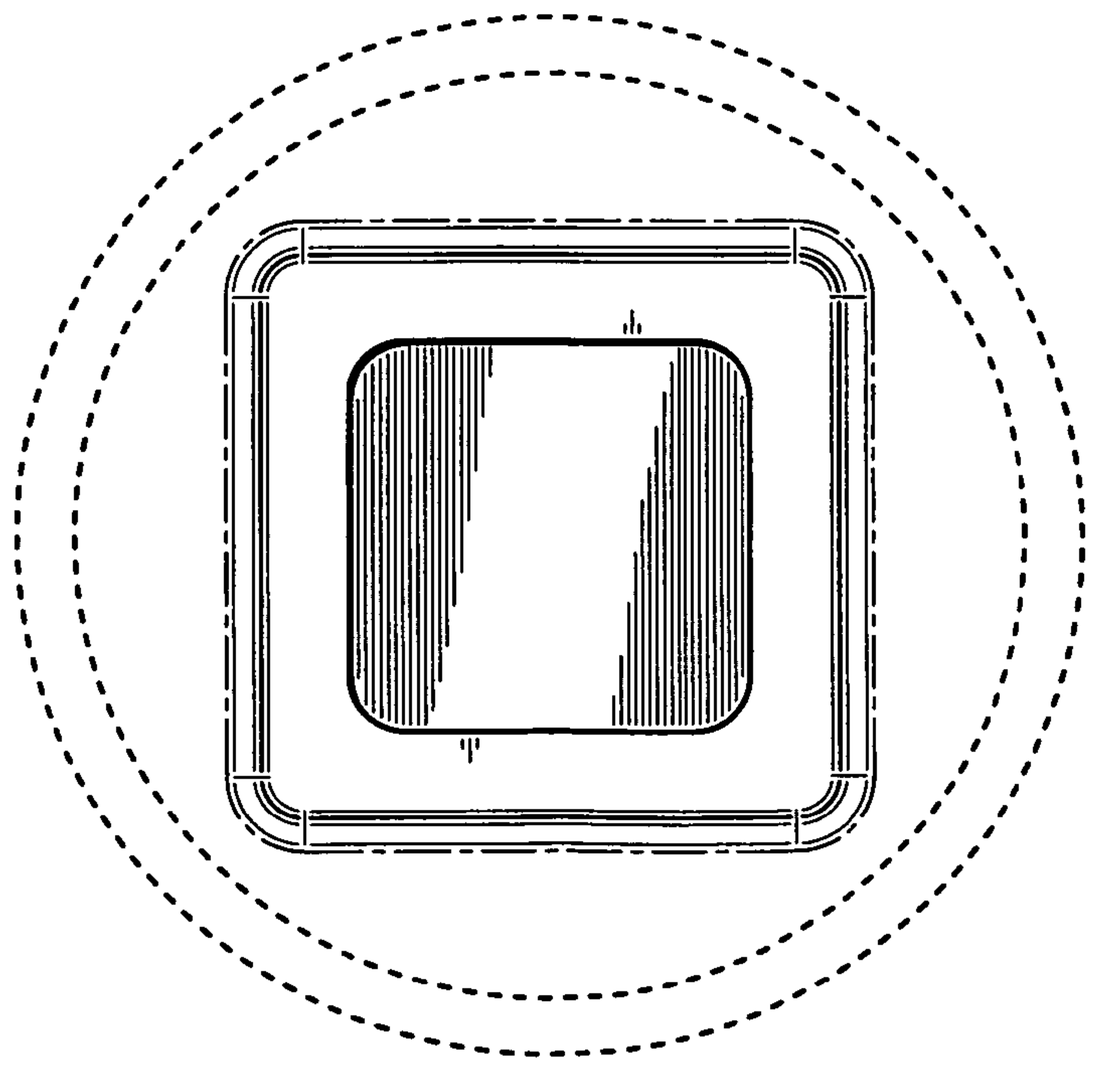

Fig. 21